PDFN5×6A N

Dual N-

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Parameter		! Symbol	" Rating	# $ Unit
Drain-Source Voltage		V_{DSS}	60	V
Drain Current		I_D(Tc=25℃)	24.5	A
Drain Current - Pulsed		I_{DM}	95	A
Gate-Source Voltage		V_{GSS}	±20	V
Single Pulsed Avalanche Energy		E_{AS}	70	mJ
Avalanche Current		I_{AS}	20	A
Power Dissipation		P_D(Tc=25℃)	12.5	W
Operating and Storage Temperature Range		T_J,T_{stg}	-55 to 150	℃
Junction-to-Ambient	t≤10	$R_{\theta JA}$	35	℃/W
Junction-to-Ambient	Steady-State		70	
Junction-to-Case	Steady-State	$R_{\theta JC}$	10	

Parameter	! Symbol	% & ' (Test Conditions	) * " Min	+ , " Typ	) - " Max	# $ Unit
Drain-Source Breakdown Voltage	BV_{DSS}					

/ Electrical Characteristics(Ta=25)

Parameter	! Symbol	% & ' (Test Conditions	) * " Min	+ , " Typ	) - " Max	# $ Unit
Turn-On Delay Time	$t_{d(on)}$	V_{GS}=10V V_{DS}=30V R_L=2.3Ω R_{GEN}=3Ω		5		ns
Turn-On Rise Time	t_r			3		
Turn-Off Delay Time	$t_{d(off)}$			19		
Turn-Off Fall Time	t_f			3		

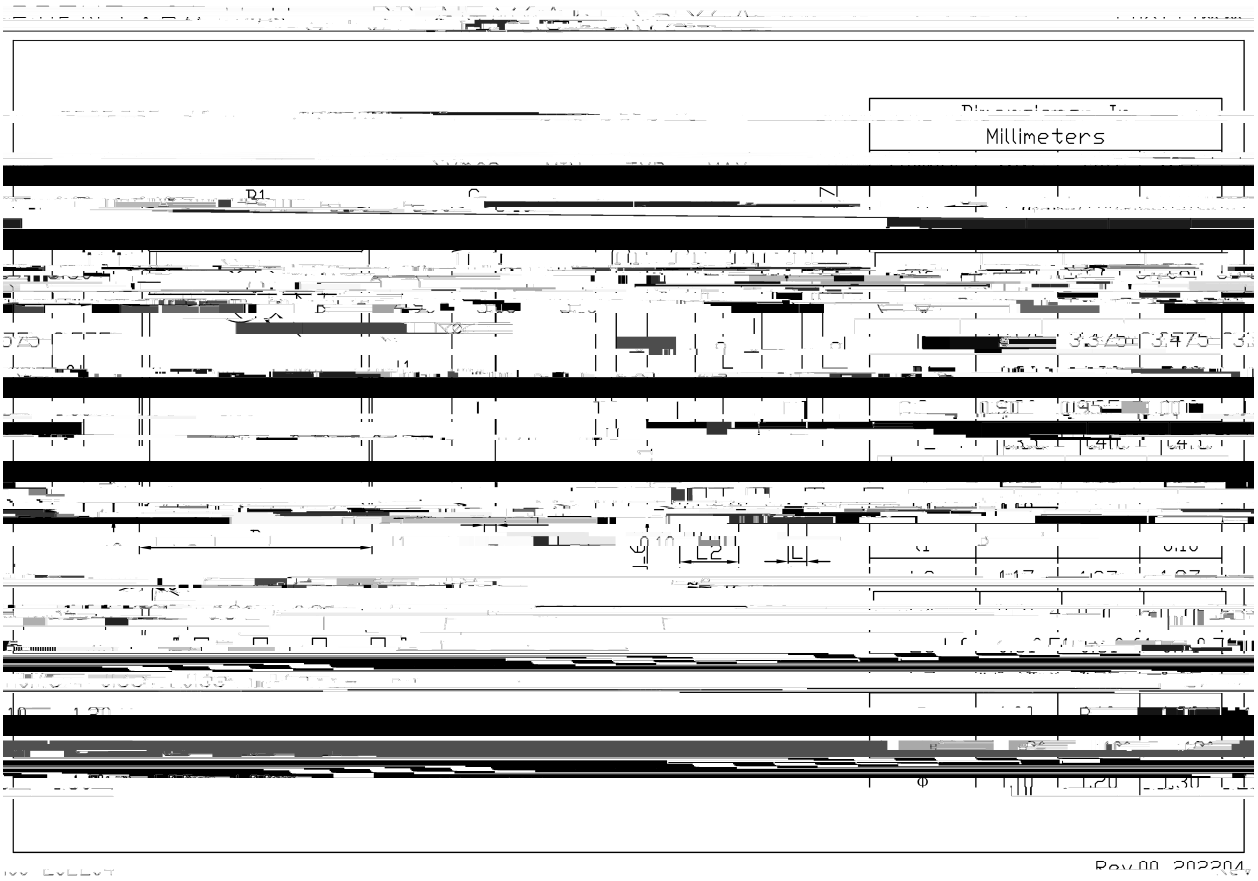
BRCS120N06SYMQ

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/ Package Dimensions



/ Marking Instructions

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( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

1	150 200 60 120sec;	1.Preheating:150~200 , Time:60~120sec.
2	255 5 5 0.5sec;	2.Peak Temp.:255 5 , Duration:5 0.5sec.
3	2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5